



# CORSTAT SIMMS SHIPPERS

- Low cost, recyclable material
- Foam minimizes damage during shipping
- Partitions can be removed to create larger cells
- ESD safe static shielding

PN	L X W X H (D)	QTY/CASE
CSP 50	14-7/8X11-15/16X1-5/8"	16
CSP 100	12 x 12 x 2"	16



## SPECIFICATIONS

These products meet and/or exceed ANSI/ESD S20.20-2021 and ANSI/ESD S541-2019.

CORSTAT		
PROPERTY	VALUE (U.S.)	TEST METHOD
Color	Black	Visual
Surface Resistance		
Buried Shielding-layer Ohms	$10^2$ - $10^3$ Ohms/sq	ANSI/ESD STM11.11-2022
Outer Dissipative-layer Ohms	$10^4$ - $10^5$ Ohms/sq	ANSI/ESD STM11.11-2022
Electrostatic Decay Rate	Avg. 0.01 sec	EIA-541
ESD Shielding	Avg. 16.49nJ	Capacitive Probe Test
Reducible Sulphur	.00035%	TAPPI-406

ASPU4300 FOAM		
PROPERTY	VALUE (U.S.)	TEST METHOD
Color	Pink	Visual
Volume Resistance	$10^5$ - $10^{11}$ Ohms/sq	ANSI/ESD STM11.12-2021
Surface Resistance	$10^5$ - $10^{11}$ Ohms/sq	ANSI/ESD STM11.11-2022
Static Decay Rate	< 2 Sec	FTMS 101-C:4046
Density	1.15-1.35 lbs/ft <sup>3</sup>	ASTM D-3574-01
Indent Force Deflection @ 25%	33-39 psi	ASTM D-3574-01
Shelf Life	Limited	

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